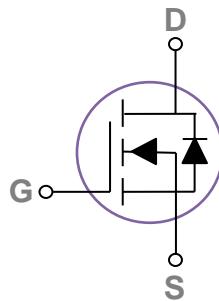


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO251 Pin Configuration



BVDSS	RDS(ON)	ID
60V	75mΩ	11A

### Features

- 60V, 11A, RDS(ON) = 75mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>Gs</sub>	Gate-Source Voltage	$\pm 20$	V
I <sub>D</sub>	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	11	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	7	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	44	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	8	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	12.8	A
P <sub>D</sub>	Power Dissipation ( $T_c=25^\circ\text{C}$ )	25	W
	Power Dissipation – Derate above 25°C	0.2	W/°C
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	5	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	60	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	---	0.05	---	$\text{V}/^\circ\text{C}$
$I_{\text{DS}}^{\text{SS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=6\text{A}$	---	60	75	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=3\text{A}$	---	70	90	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-5	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=3\text{A}$	---	4	---	S

**Dynamic and switching Characteristics**

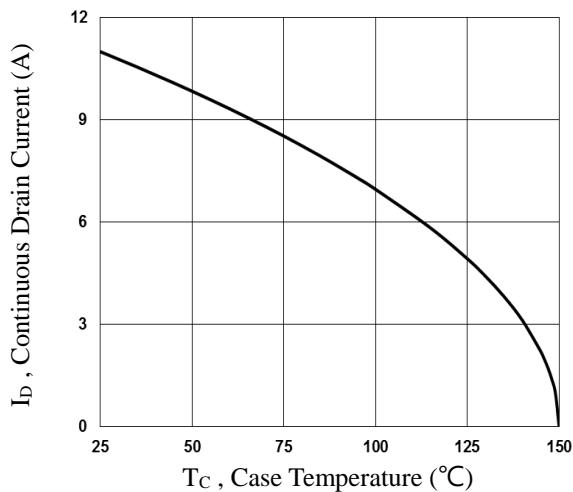
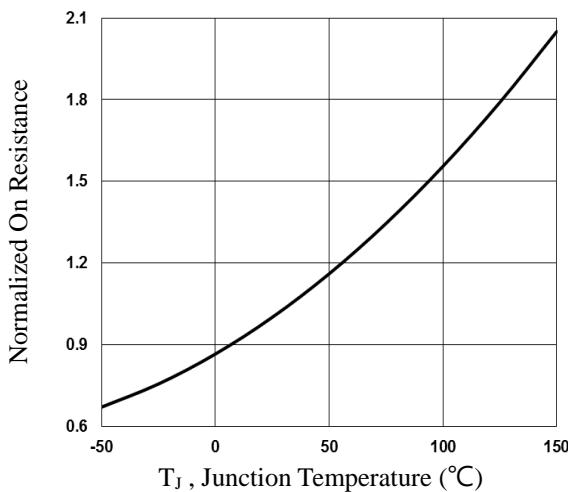
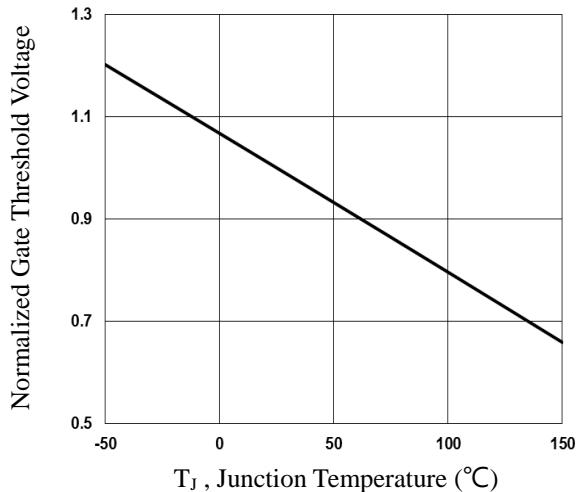
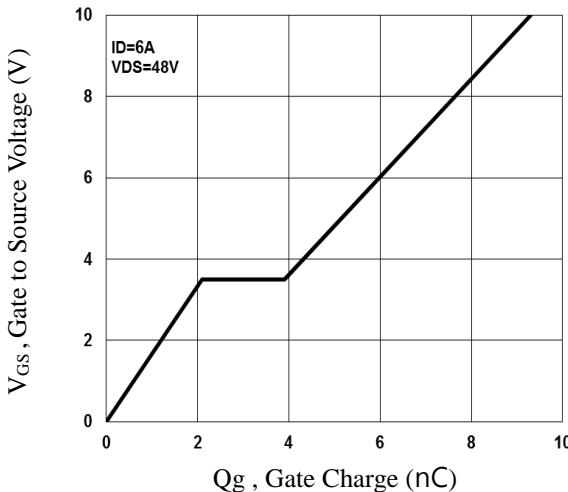
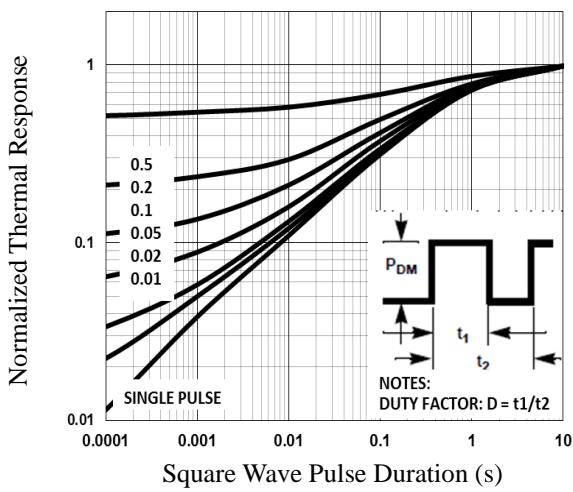
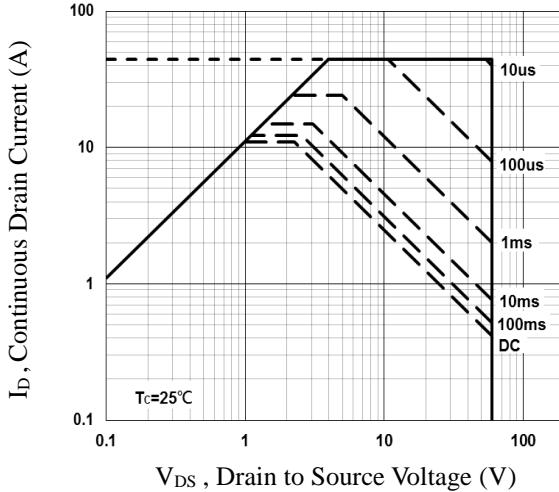
$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=6\text{A}$	---	9.3	13	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2, 3</sup>		---	2.1	3	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2, 3</sup>		---	1.8	4	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=3.3\Omega$	---	2.9	6	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	9.5	18	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2, 3</sup>		---	18.4	35	
$T_f$	Fall Time <sup>2, 3</sup>		---	5.3	10	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	500	725	pF
$C_{\text{oss}}$	Output Capacitance		---	45	65	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	16	30	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	2	4	$\Omega$

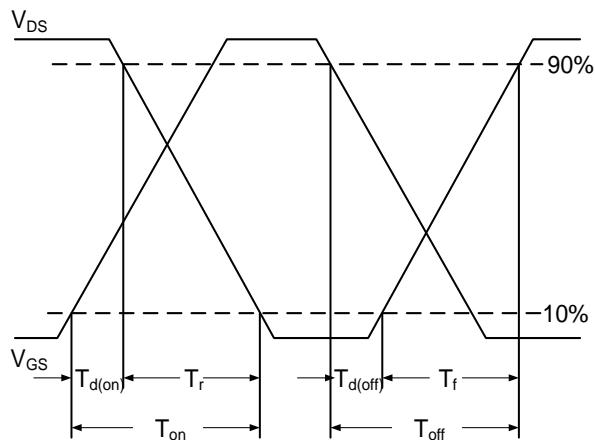
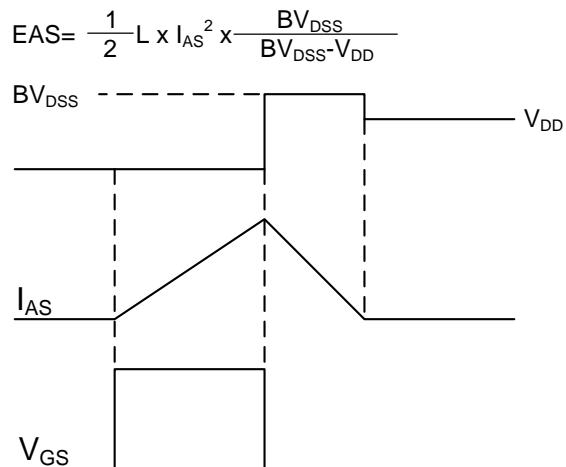
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	11	A
			---	---	44	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V
			---	23.2	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge <sup>2</sup>	$V_{\text{GS}}=30\text{V}$ , $I_s=1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	---	14.3	---	nC

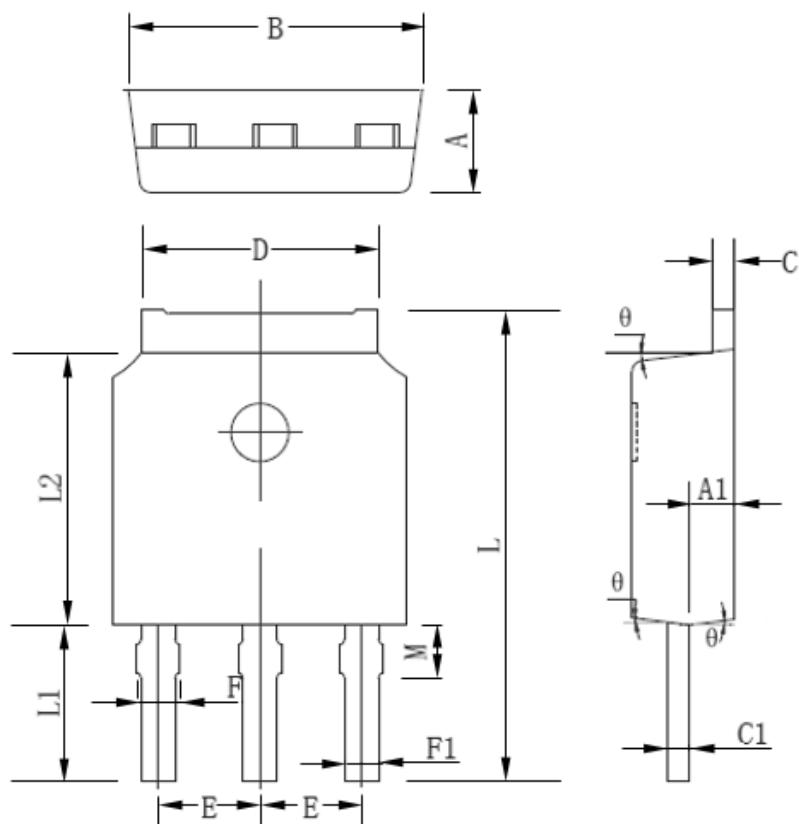
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=12.8\text{A}$ ,  $R_g=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**

**Fig.2 Normalized RDSON vs. T<sub>j</sub>**

**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 EAS Waveform**

## TO251 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.200	2.400	0.087	0.094
A1	0.910	1.110	0.036	0.044
B	6.500	6.700	0.256	0.264
C	0.460	0.580	0.018	0.023
C1	0.460	0.580	0.018	0.023
D	5.120	5.520	0.202	0.217
E	2.186	2.386	0.086	0.094
F	0.780	1.020	0.030	0.040
F1	0.660	0.860	0.026	0.034
L	10.200	10.800	0.402	0.425
L1	3.200	3.800	0.126	0.150
L2	6.000	6.200	0.236	0.244
M	1.000	1.200	0.039	0.047
θ	3°	9°	3°	9°